

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0				

NOTES:

MATERIAL:

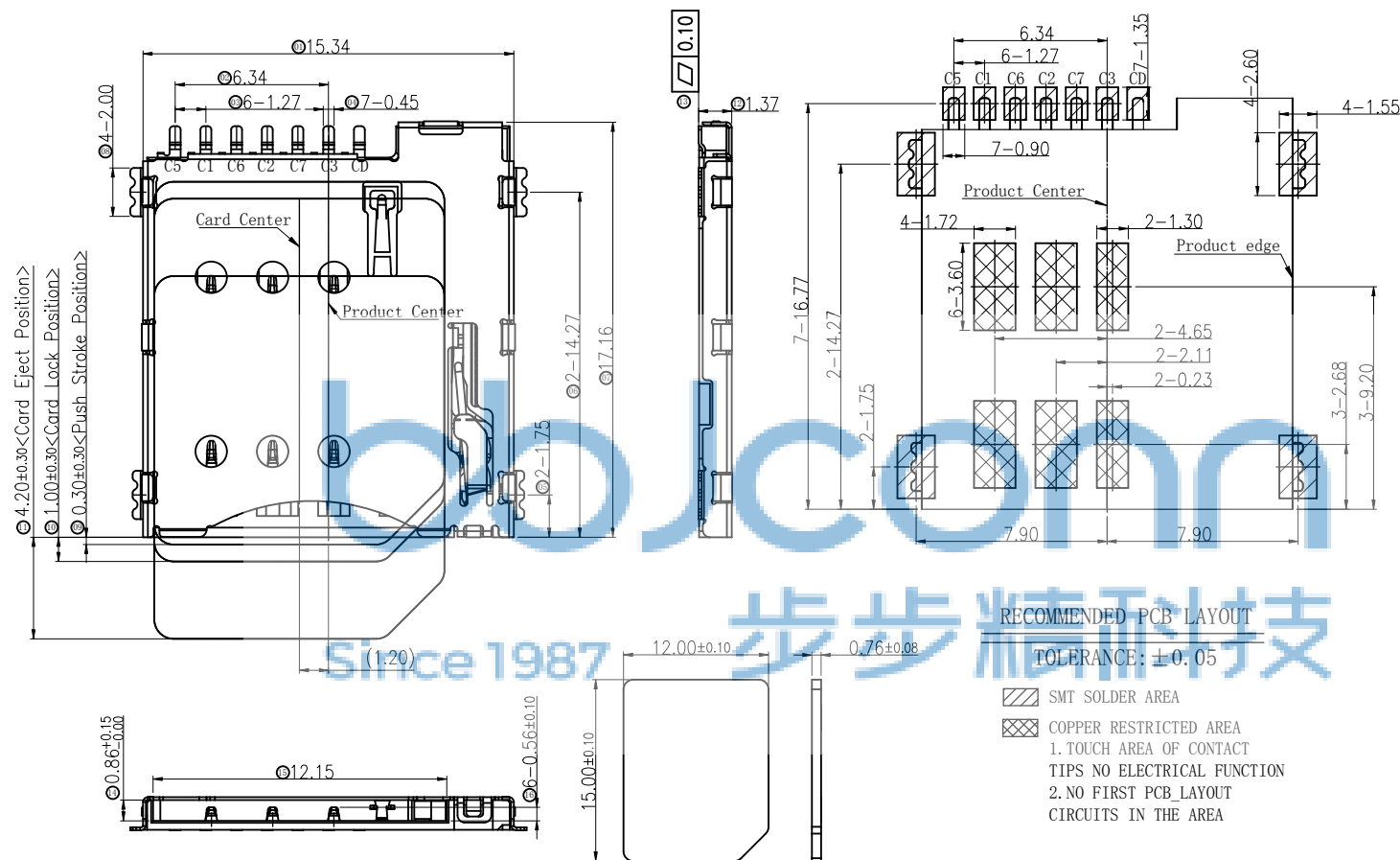
Insulator: High Temperature Thermoplastic 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

PLATING:

Contact: Plated 30u'' Ni Overall , Solder Area: Tin, Contact G/F
Shell: Plated 30u'' Ni Overall
Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5A max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20° C~+85° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩmax.
Insulation Resistance:1000MΩmin./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260° C ±5°

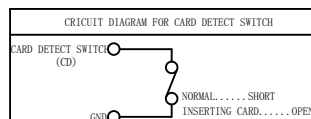
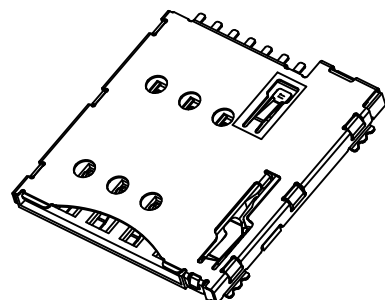


RECOMMENDED PCB LAYOUT

TOLERANCE: ±0.05

▨ SMT SOLDER AREA

▨ COPPER RESTRICTED AREA
1. TOUCH AREA OF CONTACT
TIPS NO ELECTRICAL FUNCTION
2. NO FIRST PCB LAYOUT
CIRCUITS IN THE AREA



PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

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PDWG.NO: 0302-1

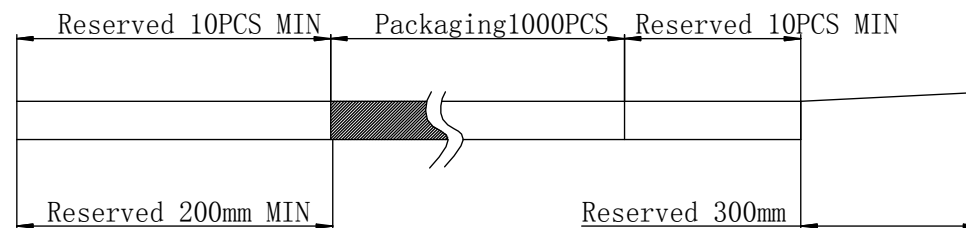
深圳市步步精科技有限公司			
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3' .X': ±2' .XX': ±1'	NAME: 卡座 MICRO-SIM PUSH-PUSH 6P 带CDPIN H=1.35 卡扣 无柱 避位	
APPD. JM_Zheng		PJ. NO.: CD.02.02-13-0001	
CHKD. TSP		SIZE: A4 DRW NO.:	
DR. LYX		FINISH: SEE NOTES	MAT'L.: SEE NOTES
		SCALE: N/A	REV.: A0 UNIT: mm PAGE: 1/2

Direction of use

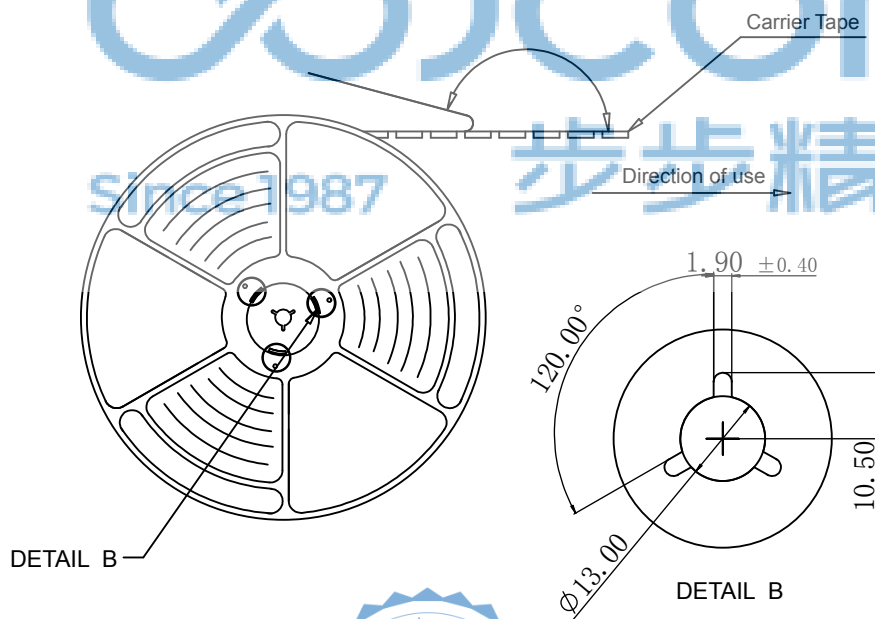
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NOTES:

- 1、Packing quantity per plate: 1000PCS/Plate
- 2、Loading and packing method

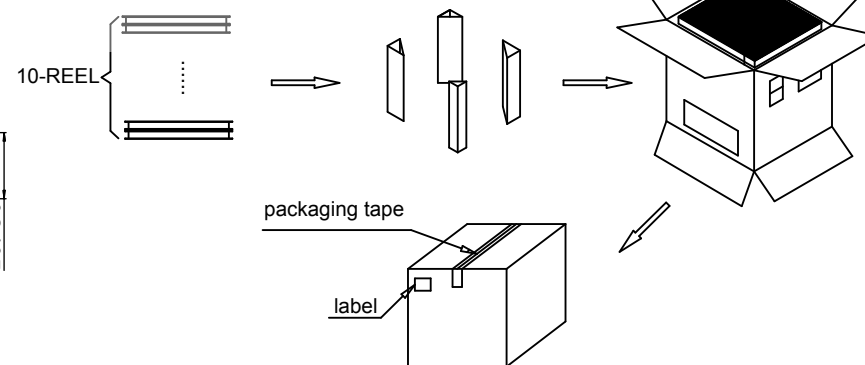


- 3、Total packaging: 10000PCS/Box



The bottom and top of the carton
Pad it with a piece of pearl cotton

BOX
350*350*340mm



Description	Quantity
Carrier band (Lucent , PET W=24 PH=20,T=0.3)	204m
Box (K=K,T=7.0,350*350*340)	1PCS
PE Bag (T=0.08mm , 730*760*730)	1PCS
Self-adhesive (W=21.3)	207m
Beam (K=K , T=7.0,95*95*290)	4PCS
Pearl Wool (340*340*18)	2PCS
REEL (BLUE , 13Inches*24mm , φ330)	10PCS
1.35H PUSH-PUSH Micro-SIM CARD<MS004-100>	10000PCS



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CHKD.	TSP	SIZE: A4 DRW NO.:	
DR.	LYX	FINISH: SEE NOTES MAT'L.: SEE NOTES	
PDWG.NO:	0302-1	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/2